LNP™ THERMOCOMP™ COMPOUND LF006

LF-1006
REGION ASIA

DESCRIPTION

LNP THERMOCOMP LF006 compound is based on Polyetheretherketone (PEEK) resin containing 30% glass fiber.

GENERAL INFORMATION	
Features	High stiffness/Strength, High temperature resistance, No PFAS intentionally added
Fillers	Glass Fiber
Polymer Types	Polyetheretherketone (PEEK)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Consumer	Commercial Appliance
Electrical and Electronics	Electronic Components, Mobile Phone - Computer - Tablets
Industrial	Electrical, Material Handling

TYPICAL PROPERTY VALUES

Revision 20231109

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL [1]			
Tensile Stress, break	176	MPa	ASTM D638
Tensile Strain, break	2	%	ASTM D638
Tensile Modulus, 50 mm/min	13230	MPa	ASTM D638
Flexural Stress	245	MPa	ASTM D790
Flexural modulus	10750	MPa	ASTM D790
Tensile Stress, break	175	MPa	ISO 527
Tensile Strain, break	1.9	%	ISO 527
Tensile Modulus, 1 mm/min	13100	MPa	ISO 527
Flexural Stress	263	MPa	ISO 178
Flexural Modulus	12700	MPa	ISO 178
IMPACT [1]			
Izod Impact, unnotched, 23°C	875	J/m	ASTM D4812
Izod Impact, notched, 23°C	117	J/m	ASTM D256
Instrumented Dart Impact Energy @ peak, 23°C	13	J	ASTM D3763
Izod Impact, unnotched 80*10*4 +23°C	57	kJ/m²	ISO 180/1U
Izod Impact, notched 80*10*4 +23°C	11	kJ/m²	ISO 180/1A
THERMAL [1]			
HDT, 0.45 MPa, 3.2 mm, unannealed	>298	°C	ASTM D648
HDT, 1.82 MPa, 3.2mm, unannealed	>298	°C	ASTM D648
CTE, -40°C to 40°C, flow	1.8E-05	1/°C	ASTM E831
CTE, -40°C to 40°C, xflow	4.68E-05	1/°C	ASTM E831

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
CTE, -40°C to 40°C, flow	1.7E-05	1/°C	ISO 11359-2
CTE, -40°C to 40°C, xflow	4.84E-05	1/°C	ISO 11359-2
HDT/Bf, 0.45 MPa Flatw 80*10*4 sp=64mm	>240	°C	ISO 75/Bf
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	>240	°C	ISO 75/Af
PHYSICAL (1)			
Density	1.54	g/cm³	ASTM D792
Moisture Absorption, (23°C/50% RH/24 hrs)	0.1	%	ASTM D570
Density	1.53	g/cm³	ISO 1183

(1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.

DISCLAIMER